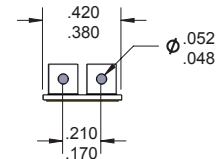
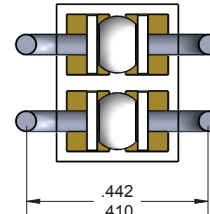
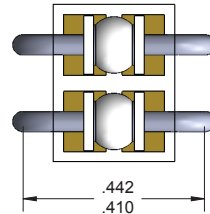
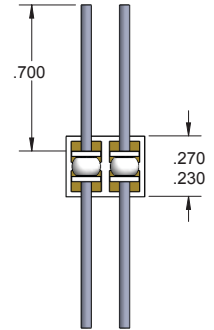
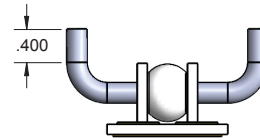
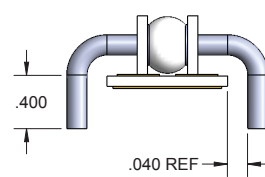
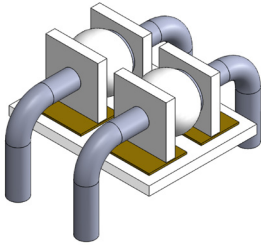


# SPA649



- Hermetically Sealed
- Void Free Construction Eliminates Die Attach, Wire Bond, Hermeticity and PIND Issues related to TO-25X and Stud Mount Packages
- Electrically Isolated Baseplate
- Weight: 1.6 g (typ)
- Smaller Footprint Than TO-254 Package
- Easy to Configure as Centertap, Doubler or Parallel Connection